



Material Composition Declaration

EPC2306

Company Name	Efficient Power Conversion (EPC)	Issue Date:	8/23/2024
Contact Name:	Yanping Ma	Contact Title:	VP Quality
Contact Phone:	(310) 615-0280	Contact Email:	yanping.ma@epc-co.com
Part Weight:	30.5 mg	Type of Product:	eGaN FET in FCQFN package

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	4.9583	16.2649	17.1586	162649
	Silicon oxide	7631-86-9	0.0417	0.1367		1367
	Silicon nitride	12033-89-5	0.0320	0.1049		1049
	Gallium nitride	25617-97-4	0.0279	0.0914		914
	Aluminum	7429-90-5	0.0705	0.2313		2313
	Aluminum nitride	24304-00-5	0.0043	0.0140		140
	Titanium	7440-32-6	0.0026	0.0085		85
	Titanium nitride	25583-20-4	0.0161	0.0528		528
	Copper	7440-50-8	0.0012	0.0039		39
	Tungsten	7440-33-7	0.0077	0.0252		252
	Polyimide		0.0686	0.2250	2250	
Under Bump Metal	Titanium	7440-32-6	0.0005	0.0016	0.0174	16
	Copper	7440-50-8	0.0048	0.0158		158
Solder Bump	Copper	7440-50-8	0.4057	1.3310	2.0671	13310
	Nickel	7440-02-0	0.0288	0.0945		945
	Tin	7440-31-5	0.1921	0.6300		6300
	Silver	7440-22-4	0.0035	0.0115		115
Package	Copper	7440-50-8	11.7262	38.4661	80.7569	384661
	Iron	7439-89-6	0.3007	0.9863		9863
	Mold Compound		11.9056	39.0544		390544
	Tin	7440-31-5	0.6859	2.2501		22501
Sum in total:			30.4846	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.